

## „Dynamic Profiling PLUS“ – worldwide innovation from ASSCON

05. Mai 2015 – On the occasion of the international fair with congress SMT Hybrid packaging 2015 from May 05<sup>th</sup> to May 07<sup>th</sup>, 2015 in Nurnberg, the German vapor phase – reflow – soldering systems specialist ASSCON Systemtechnik-Elektronik GmbH – in brief ASSCON – presents in hall 7 on stand 339 again an absolutely innovative novelty. Presented will be „Dynamic Profiling PLUS“, a further development of the patented automatic temperature profiling and active control system „Dynamic Profiling“, which ensures the absolute process safety in serial operation.



The control system Dynamic Profiling permits real time measuring of every soldering process on product level and the automatic creation and control of the soldering profile. Measuring standards are used, which are heated in the system together with soldering product. The temperature and heating behavior of the product can thus be ascertained and recorded with no risk of destruction. The measuring standard behavior is used as a variable for active profile control during the soldering process.

The new Dynamic Profiling Plus provides all prerequisites that the soldering system sets fully automatic to the soldering profile, given from the operator and a reference measurement. Elaborate manual settings and adjustments of the soldering profile from the operator have therefore definitely become a thing of the past. Even in vapor phase vacuum soldering systems, this innovative technology can substantially facilitate the daily work in the production.

### „Dynamic Profiling PLUS“ brings significant advantages

With „Dynamic Profiling Plus“ the operator can already solder successfully at assemblies of the first lots according to the given soldering profile. Already from the start the risk of destruction of assemblies e.g. through too long times over Liquidus is excluded absolutely safely. Furthermore, the costs of production are substantially reduced and expensive test measurements are dropped. The purchasing and the storage of test assemblies can be also reduced to a minimum - a further contribution to avoid unnecessary expenses.

The automatic and continuous monitoring of each soldering profile in real time ensures a reliable and constant high soldering quality (100% First Pass Yield) for production of efficient and long lasting products.



Additionally mentioned ASSCON-Managing Director Claus Zabel: „Dynamic Profiling PLUS is an excellent tool for prototyping and benchmarking. It assists the user for fast and efficient access for new customers, products and markets. Since an immediate switch of the line at product change is possible, a result for the user is maximum flexibility and operation time (up time) in the electronic production, lower total cost and therefore a higher competitive position.“

### A Salute to Industry 4.0.

For the vapor phase soldering process, „Dynamic Profiling PLUS“ provides an important component to minimize the production preparation, while the internal measuring system for creating and monitoring the soldering profiles configures itself and optimizes the measured temperature behavior of the assembly. It is self-evident that the data recorded via „Dynamic Profiling PLUS“ can be saved in databases for backup and traceability. „Dynamic Profiling PLUS“ is therefore an important step for the vapor phase process up to Industry 4.0.